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1-2. Package

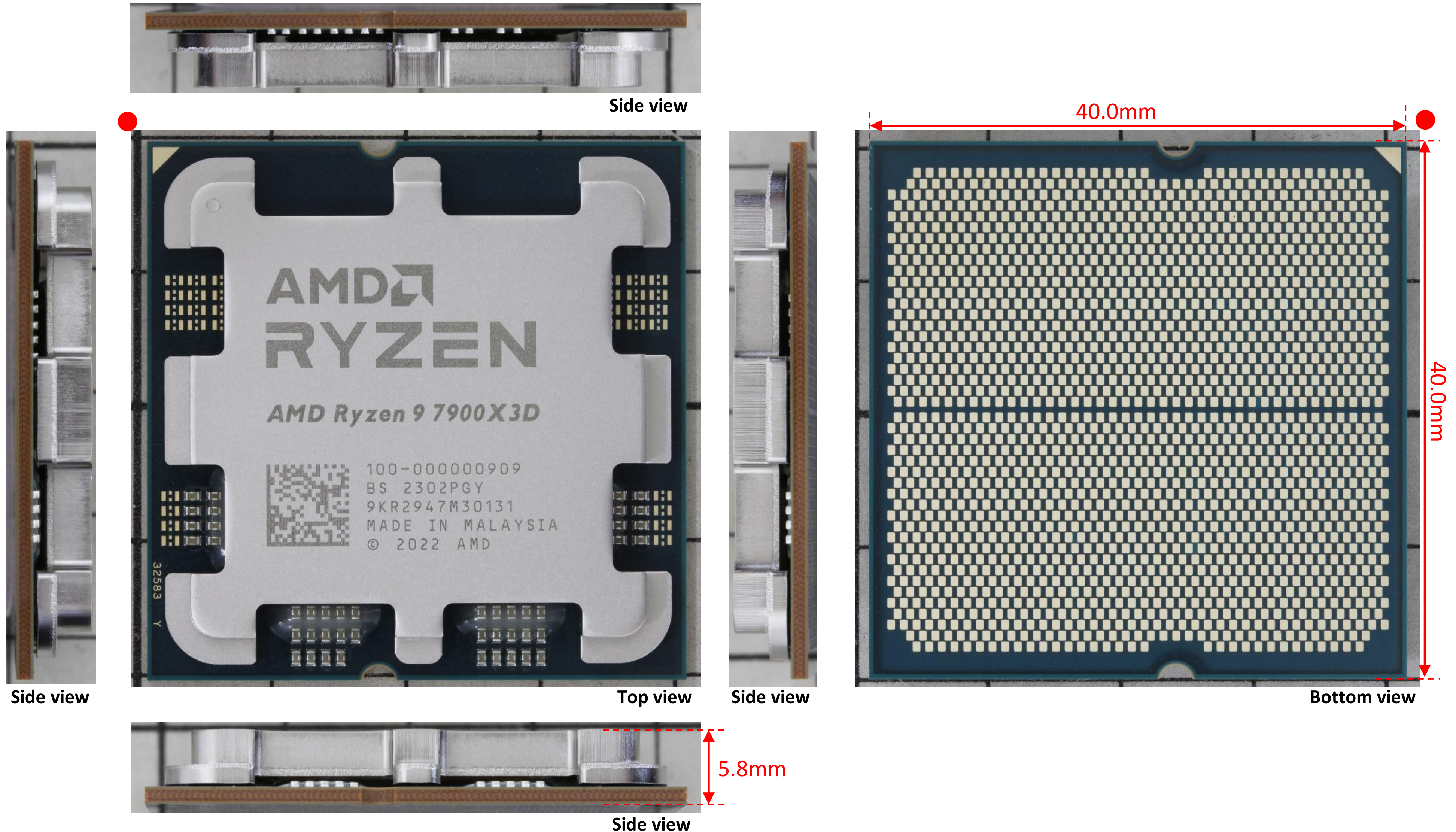


Fig. 1-2-1 Package

1-3. X-ray

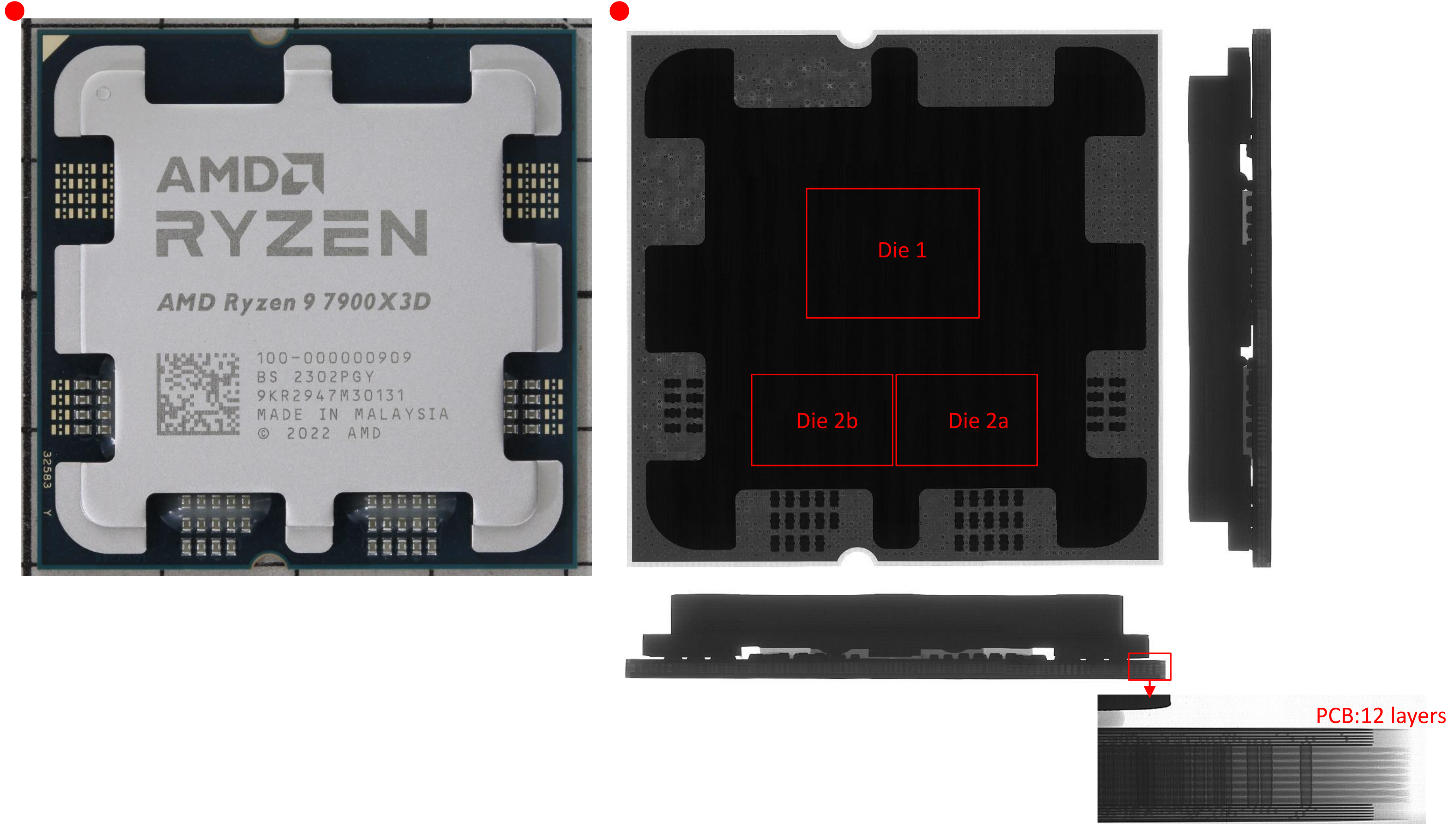


Fig. 1-3-1 X-ray

1. Product overview

1-4. Package after heat sink removal

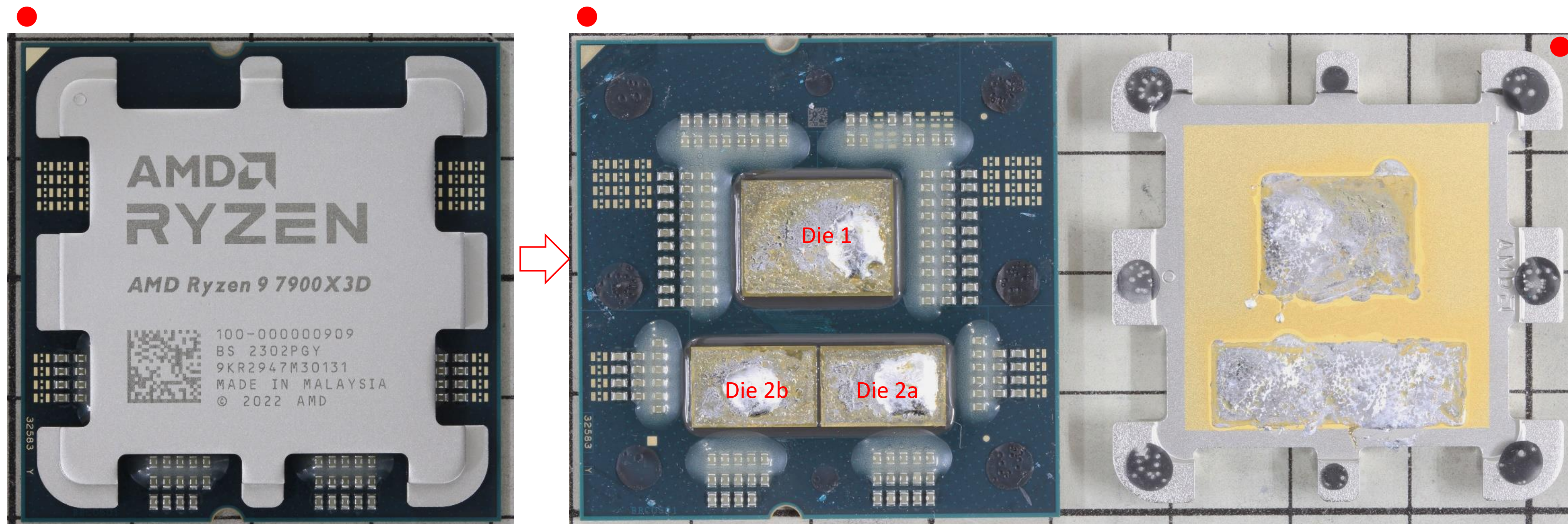


Fig. 1-4-1 Package after heat sink removal

● = 位置合わせ

1-4. Package after heat sink removal

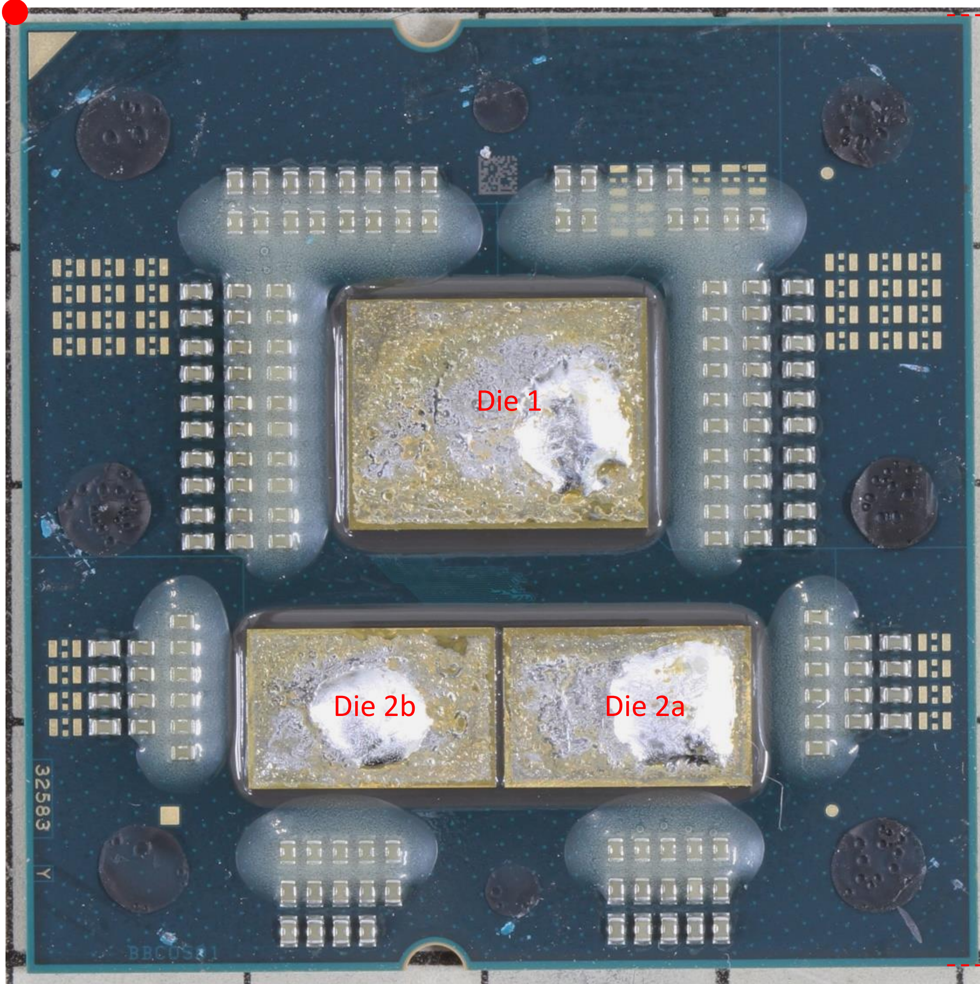


Fig. 1-4-4 Package after heat sink removal

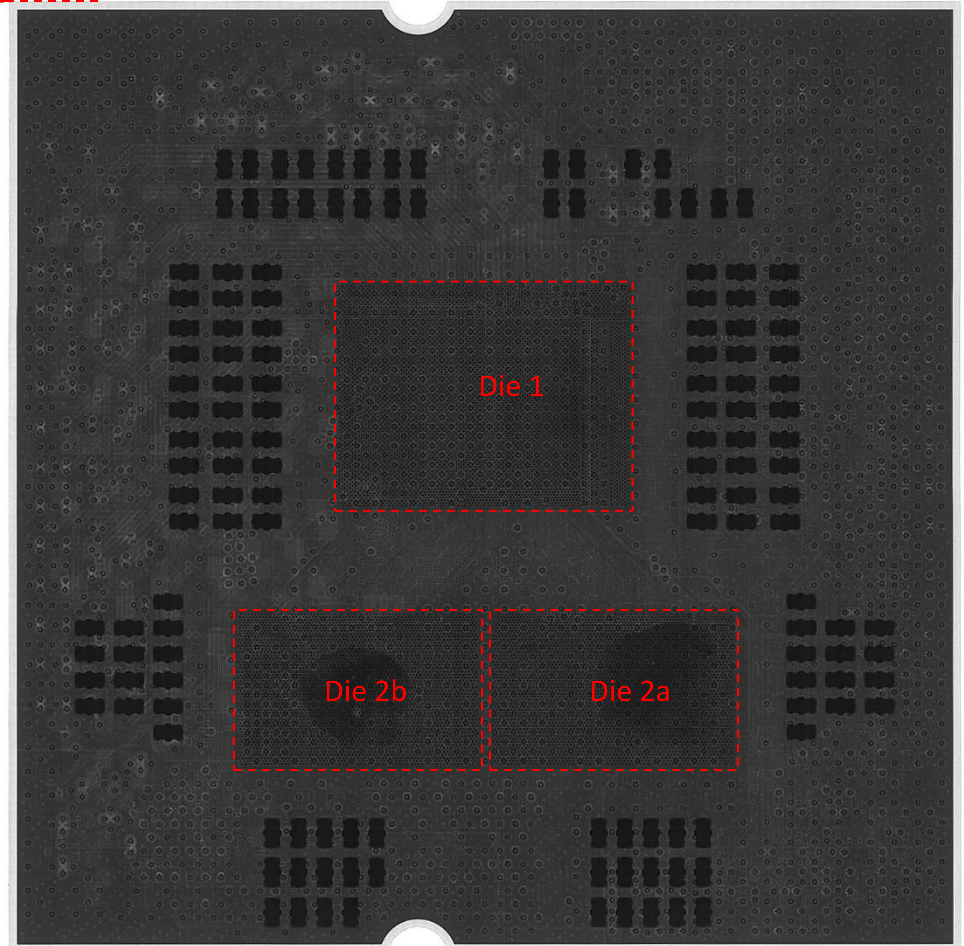


Fig. 1-4-5 X-ray (Package after heat sink removal後)

2. IC

2-1. Die 1

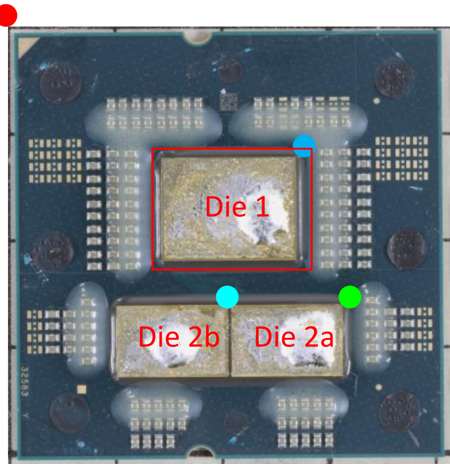
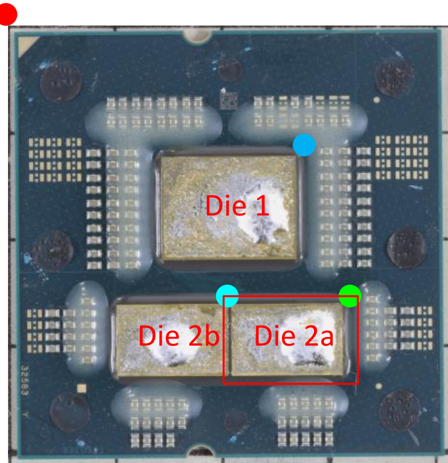


Fig. 2-1-2 Die 1 Die marking

Fig. 2-1-1 Die 1

2-2. Die 2a



A

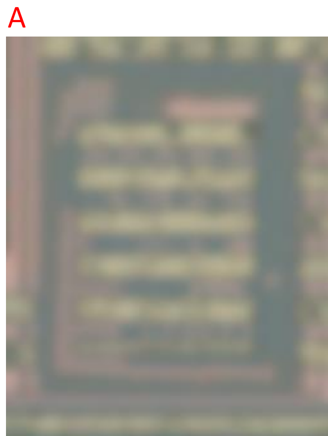


Fig. 2-2-2 Die 2a Die marking

Fig. 2-2-1 Die 2a

Fig. 2-2-3 Cross section

3. Plane view analysis

3-1. TSV

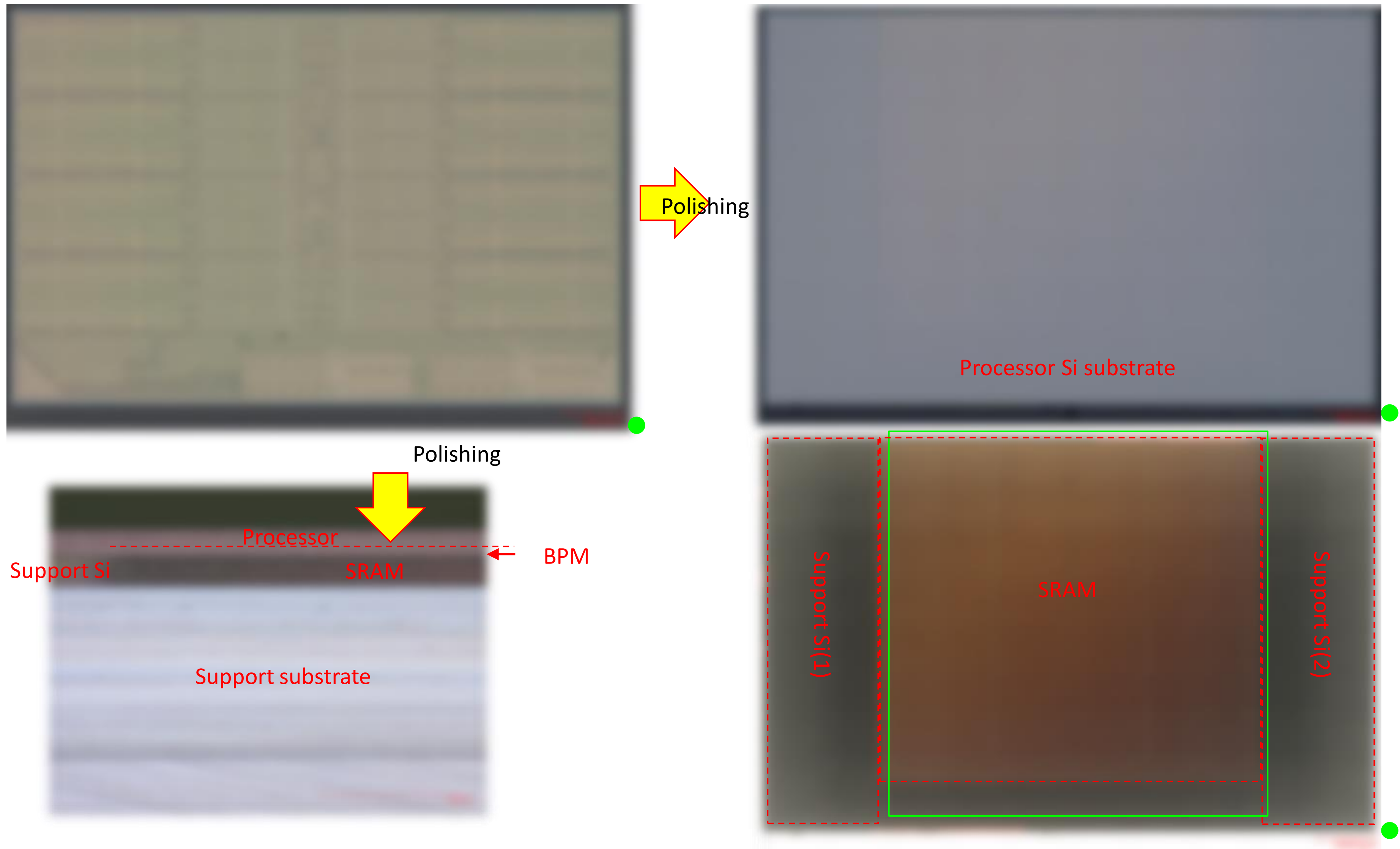


Fig. 3-1-1 Die 2a after polishing

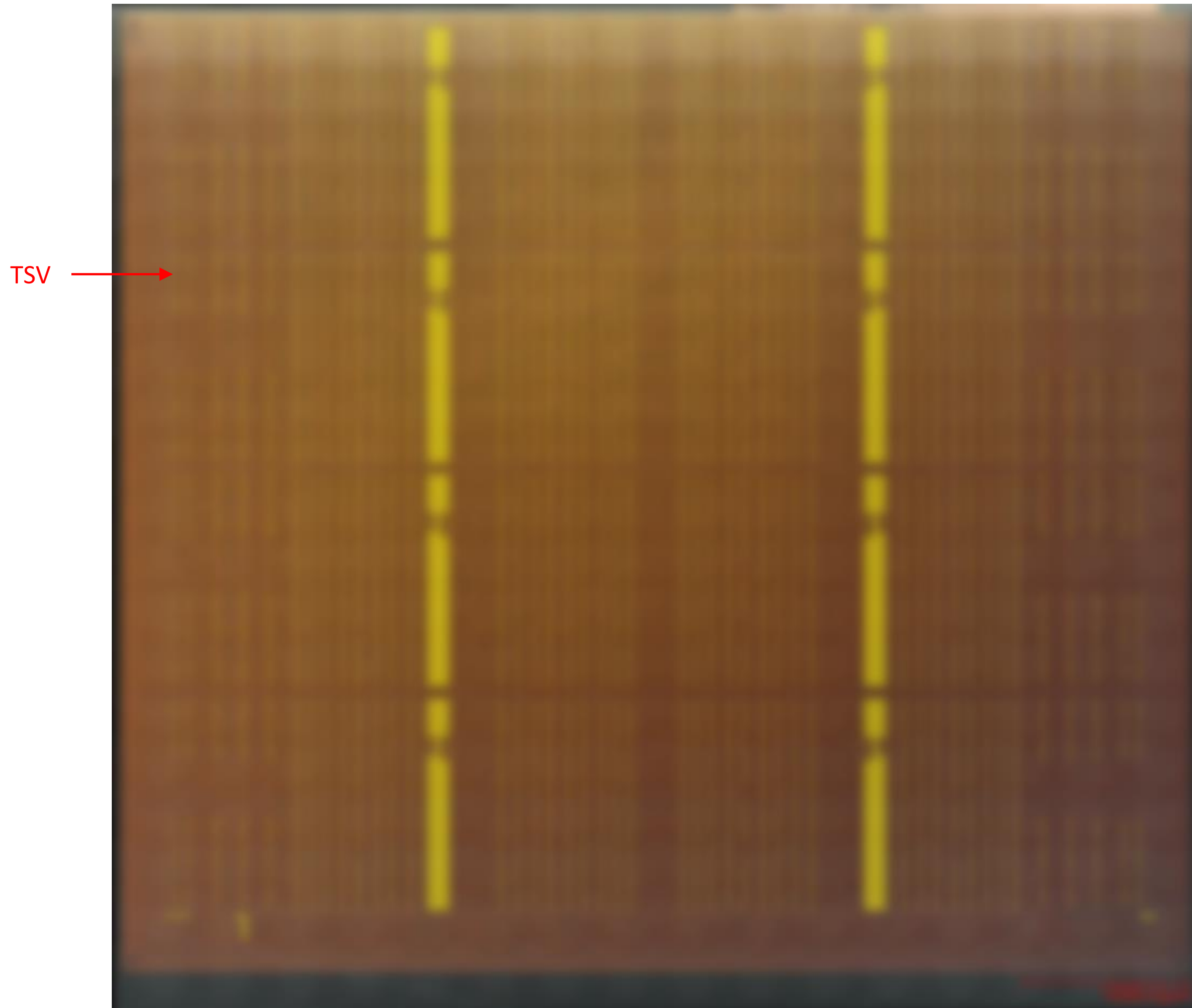


Fig. 3-1-2 Die 2a

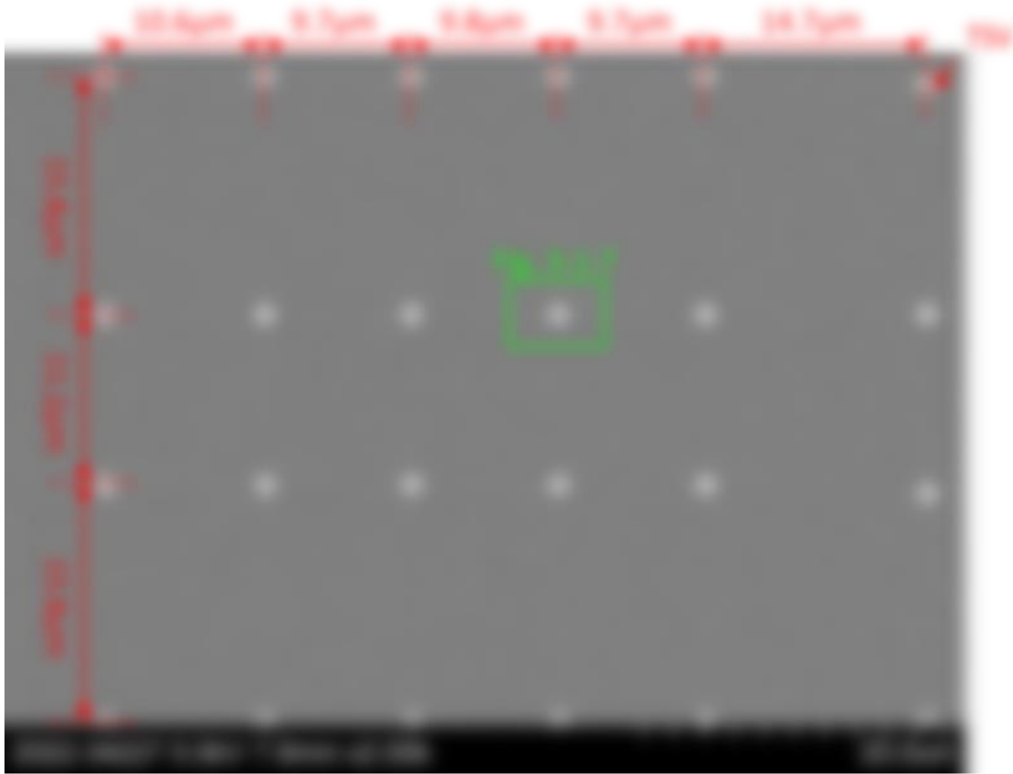


Fig. 3-1-6 IC2 TSV SEM

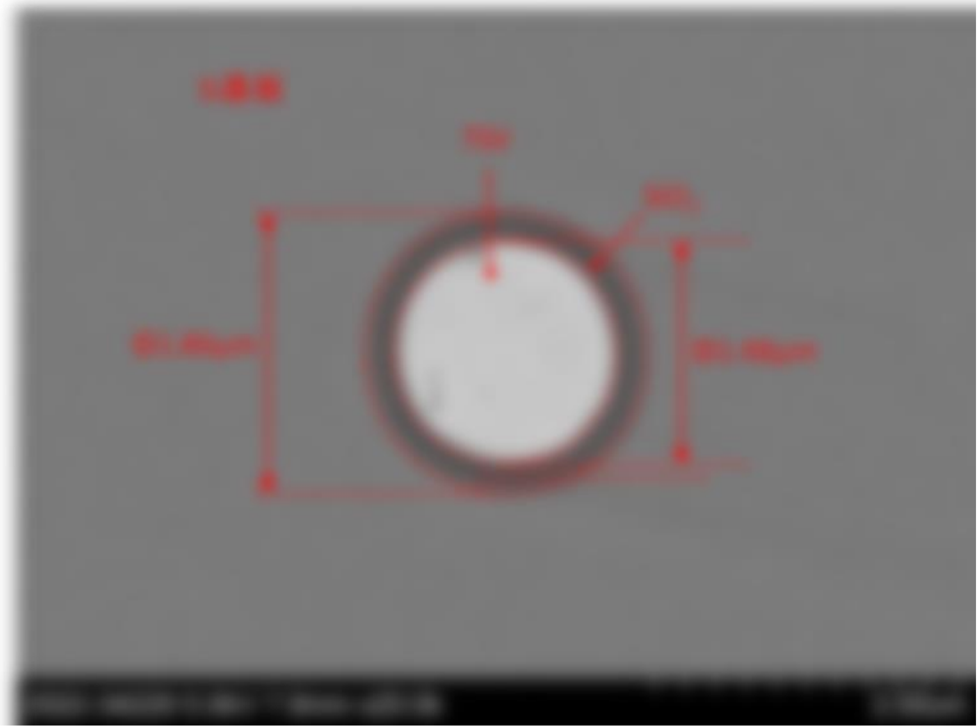


Fig. 3-1-7 IC2 TSV SEM

3-2. BPM

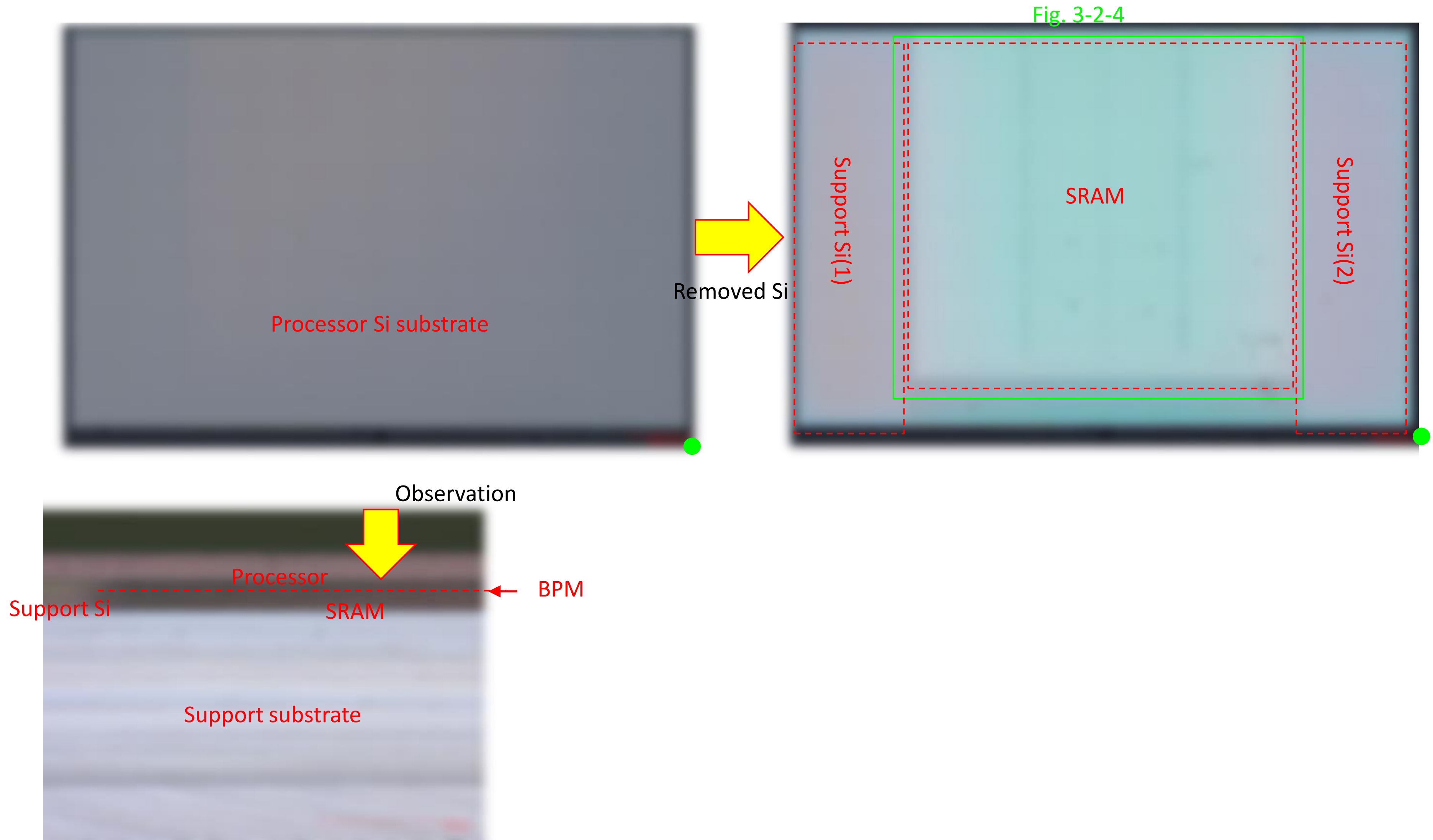


Fig. 3-2-1 IC2 Processor Si substrate除去 OM像

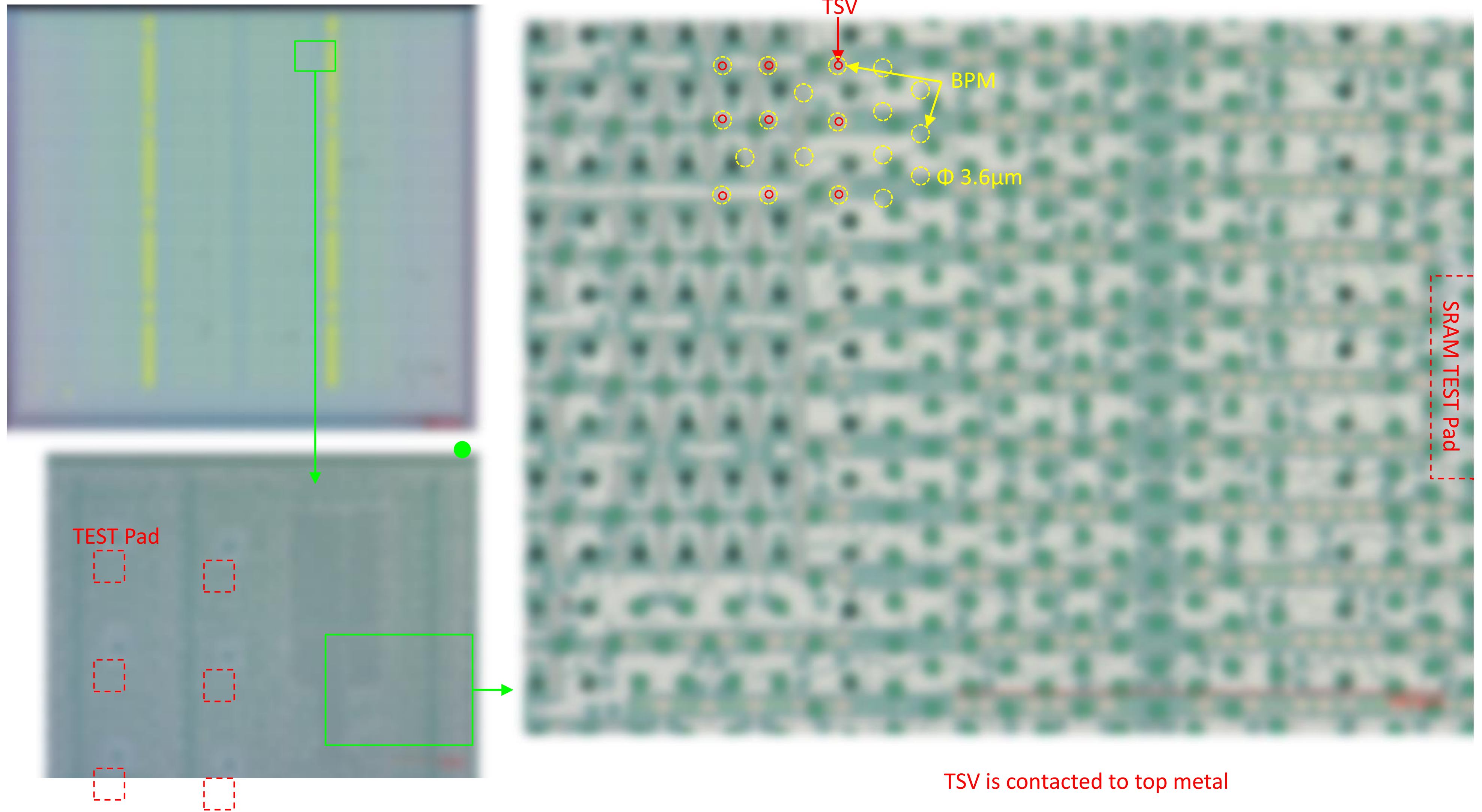


Fig. 3-2-5 IC2 SRAM BPM